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INVESTOR CONFERENCE

SCALING THE AI x CONNECTIVITY CONVERGENCE WITH ENGINEERED SUBSTRATES

Barcelona | March 2026

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DISCLAIMER

This document is provided by Soitec (the "**Company**") for information purposes only. The Company's business operations and financial position are described in the Company's 2024-2025 Universal Registration Document (which notably includes the Annual Financial Report) and the Company's 2025-2026 Half-Year Report.

The 2024-2025 Universal Registration Document was filed with the French stock market authority (Autorité des Marchés Financiers, or AMF) on June 11, 2025 and the 2025-2026 Half-Year Report on November 29, 2025. The French version of the 2024-2025 Universal Registration Document and the 2025-2026 Half-Year Report, together with English courtesy translation for information purposes, is available for consultation on the Company's website (www.soitec.com), in the section Investors - Regulated Information - Financial reports and results & other regulated releases.
Your attention is drawn to the risk factors described in Chapter 2.1 (Risk factors and controls mechanism) of the 2024-2025 Company's Universal Registration Document.

This document contains summary information and should be read in conjunction with the 2024-2025 Universal Registration Document and the 2025-2026 Half-Year Report.

This document contains certain forward-looking statements. These forward-looking statements relate to the Company's future prospects, developments and strategy and are based on analyses of earnings forecasts and estimates of amounts not yet determinable. By their nature, forward-looking statements are subject to a variety of risks and uncertainties as they relate to future events and are dependent on circumstances that may or may not materialize in the future. Forward-looking statements are not a guarantee of the Company's future performance. The occurrence of any of the risks described in Chapter 2.1 (Risk factors and controls mechanism) of the 2024-2025 Universal Registration Document may have an impact on these forward- looking statements. In particular, ongoing geopolitical tensions as well as persistent inflationary pressures, monetary policy and exchange rates uncertainty, and supply chain disruptions, may have consequences that are more significant or longer-lasting than currently anticipated in these forward-looking statements.

Any market shares presented herein are based on internal estimates and relate to that share of the market segment served and addressed by Soitec which may exclude broader segments of the market and competing technologies.

The Company's actual financial position, results and cash flows, as well as the trends in the sector in which the Company operates may differ materially from those contained in this document. Furthermore, even if the Company's financial position, results, cash-flows and the developments in the sector in which the Company operates were to conform to the forward- looking statements contained in this document, such elements cannot be construed as a reliable indication of the Company's future results or developments.
The Company does not undertake any obligation to update or make any correction to any forward-looking statement in order to reflect an event or circumstance that may occur after the date of this document.

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#01

AI x CONNECTIVITY CONVERGENCE

#02

ENGINEERED SUBSTRATES OPPORTUNITIES

#03

SOITEC TECHNOLOGY LEADERSHIP

01 AI x CONNECTIVITY CONVERGENCE

THE AI x CONNECTIVITY CONVERGENCE IS DRIVING DATA TRAFFIC GROWTH

High-adoption GenAI drives traffic

Widely adopted, data-intensive GenAI apps will drive global mobile network traffic growth

Uplink-driven spectrum expansion

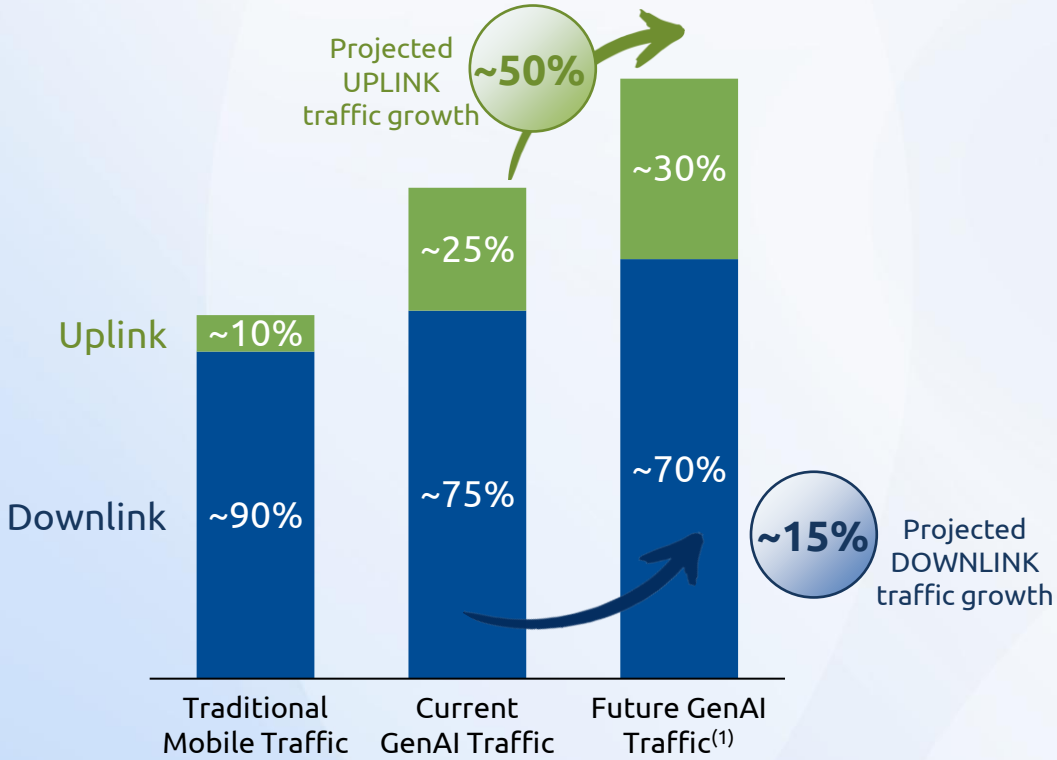
Net-new traffic growth will need network planning and broader band spectrum to support rising uplink needs

Connectivity enables AI experience

Differentiated connectivity will be crucial to deliver high-quality experiences for personalized AI agents and conversational apps

THE RISE OF GenAI

BOOSTING DEMAND FOR UPLINK AND DOWNLINK TRAFFIC



AI-AUGMENTED

CONSUMER

Personal assistant
Real-time translation
AR navigation
Content curation

ENTERPRISE

Workflow automation & optimization
Knowledge retrieval assistant
Data reconciliation
Improved decision making
Communications management

Constant bi-directional interactions(2)
(AI inference loop)

UPLINK + DOWNLINK

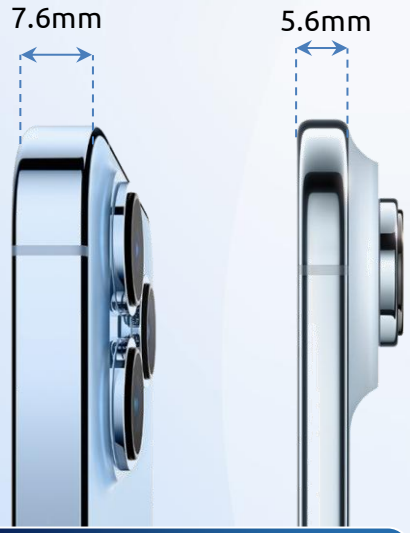
(1) assuming widespread adoption of multimodal AI assistants & AR glasses

Source: Ericsson Mobility Report 2025, Soitec

(2) vs. punctual & user-driven interactions, using mostly downlink, before the AI era

EXTENSION TO NEW FORM FACTORS: SLIMMER, WIDER, MORE CONNECTED

DRIVING NEW REQUIREMENTS AT THE SEMICONDUCTOR LEVEL



Thinner smartphones

iPhone 13 vs iPhone Air 17

Emerging foldable devices

Samsung Z Fold 7

More connected devices

Apple Watch Series 11

Enhanced Wireless functionality

Next-gen AI glasses with 5G connectivity in the branch

POWER, PERFORMANCE, AREA, COST

Key drivers, from systems to substrates

Source: Apple, Samsung, Meta Ray-Ban

NEW HABITS DRIVING EXPONENTIAL GLOBAL DATA GROWTH

CLOUD, HYBRID WORK, STREAMING, AUTONOMOUS VEHICLES, IoT, WEARABLES…

VOLUME OF DATA CREATED, CONSUMED AND STORED WORLDWIDE (in zettabytes)

Source: IDC, statista.com

REDEFINING THE RF FRONT END REQUIREMENTS

A STRUCTURAL TRANSFORMATION PUSHING THE LIMITS OF CONNECTIVITY PERFORMANCE & DIFFERENTIATION

GenAI + extension to new form factors

Transforming mobile networks from content delivery platforms into real-time distributed AI systems

ENHANCED CONNECTIVITY

Facing increased uplink & continuous downlink traffic

- Low latency
- Higher uplink data rates
- Higher downlink data rates
- Extended spectrum

AI at the EDGE

Increasing constraints on thermal management & footprint optimization

- Real-time processing
- Increased power consumption
- Extended memory & NPU content

Increased BoM, enhanced thermal management & footprint optimization requirements

Source: Soitec

AI x CONNECTIVITY – MOVING TO AN ALL-CONNECTED WORLD

5G PERFORMANCE vs 4G

x100 NETWORK CAPACITY

x10 SPEED

x10 FASTER RESPONSE TIME

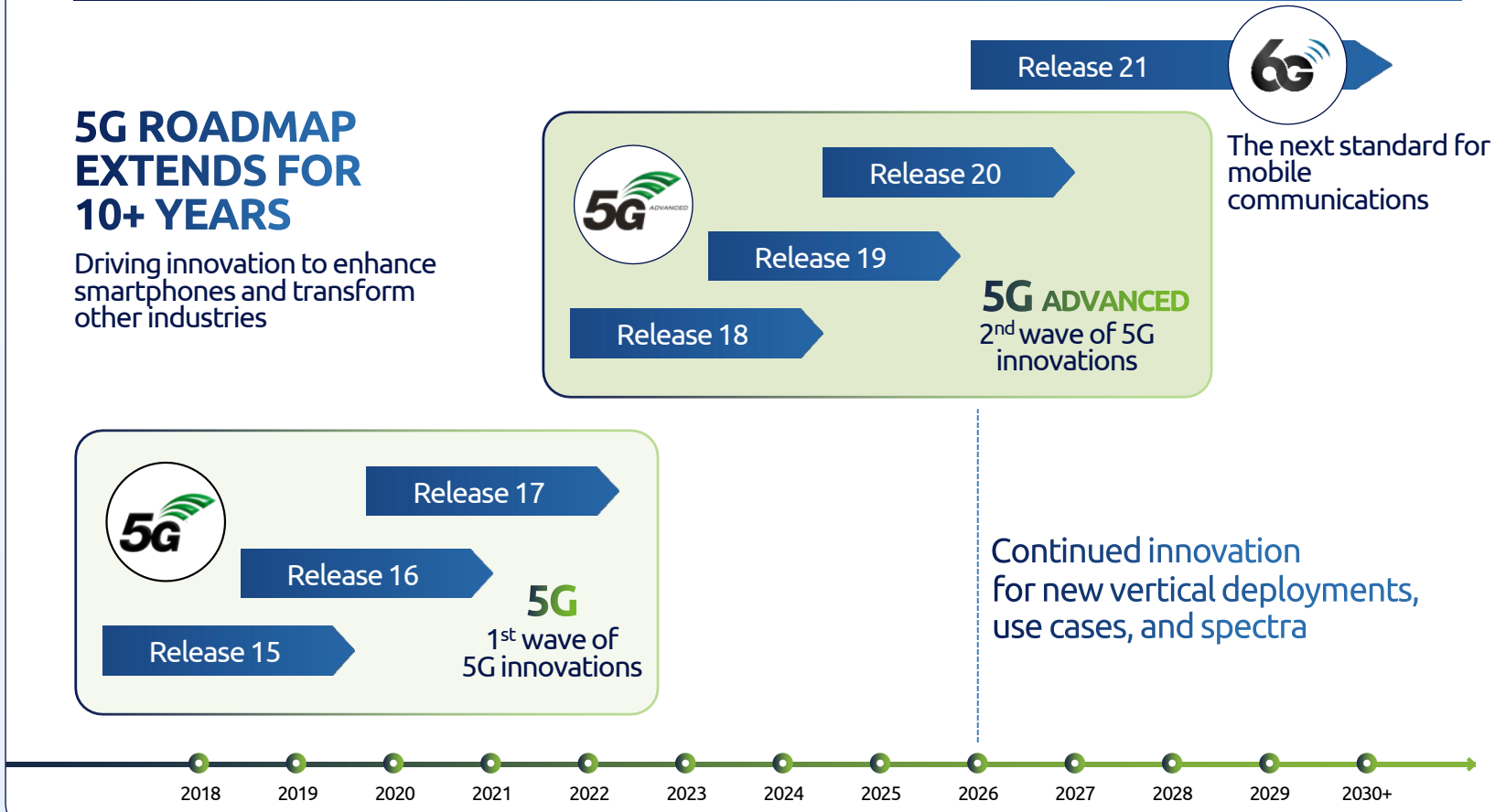
x10 CONNECTED DEVICES

x10 LESS ENERGY PER DATA

5G to 6G – PREPARING FOR A NEW ERA

5G ROADMAP EXTENDS FOR 10+ YEARS

Driving innovation to enhance smartphones and transform other industries

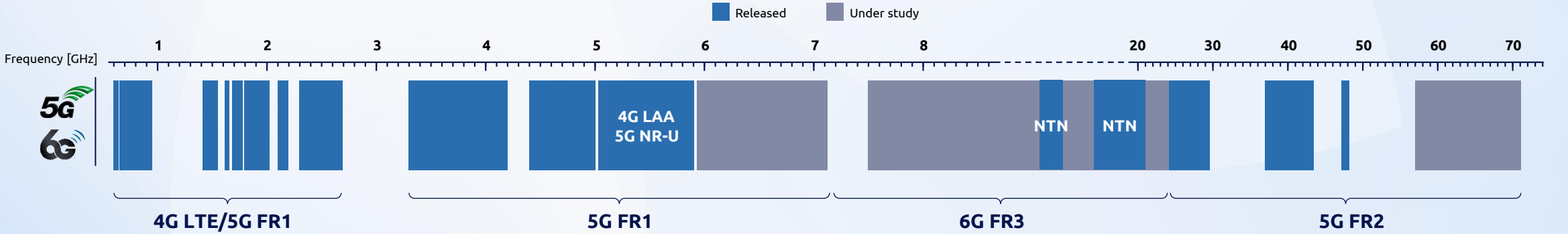


Source: Qualcomm, Ericsson

AI x CONNECTIVITY – MORE BANDS TO ACCOMMODATE GROWING DATA TRAFFIC

MAXIMIZING MULTI-BAND UTILITY: FOR EACH BAND, A USE CASE

Over the last 10 years, mobile data traffic has more than doubled on average every second year



Low-bands FR1

Below 1GHz (~20MHz BW)

Low data rate coverage
Low power IoT

Mid-bands FR1

1-7GHz (~100MHz BW)

Large area coverage
Macro capacity
Wide area location

Upper-Mid-bands FR3

7-24GHz (~500MHz BW)

Macro capacity
Fixed Wireless Access (FWA)
Non-Terrestrial Network (NTN)
Wide area sensing

Upper-Mid-bands FR2

24-71GHz (~800MHz BW)

Capacity hotspots
Dense urban outdoors (mmW)
Fixed Wireless Access (FWA)
Local sensing

Supports **5x** traffic load vs 5G

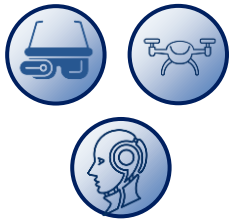
Downlink speed **3x** faster vs 5G

Cost-effective capacity – no further network densification

Source: Soitec

AI x CONNECTIVITY – SCALING NETWORK CAPABILITIES TO MEET MULTIMODAL DEMAND

NETWORK EVOLUTIONS BEYOND MOBILE BROADBAND, A MULTI-YEAR TAILWIND

	CONNECTIVITY	APPLICATIONS	MEGATRENDS
5G	Extended 4G coverage 5G mmWave spectrum NTN bands (remote areas) Downlink MIMO (antenna) **DOWNLOAD**		Mobile broadband
5G ADVANCED	6GHz extended spectrum RedCap Uplink MIMO (antenna) **UPLOAD + DOWNLOAD**		Agentic AI
6G	Extended FR3 spectrum eRedCap **UPLOAD + DOWNLOAD**		Immersive sensing

STRUCTURAL DRIVERS

- Premiumization
- New form factors
- Footprint optimization
- Power management
- Bandwidth expansion

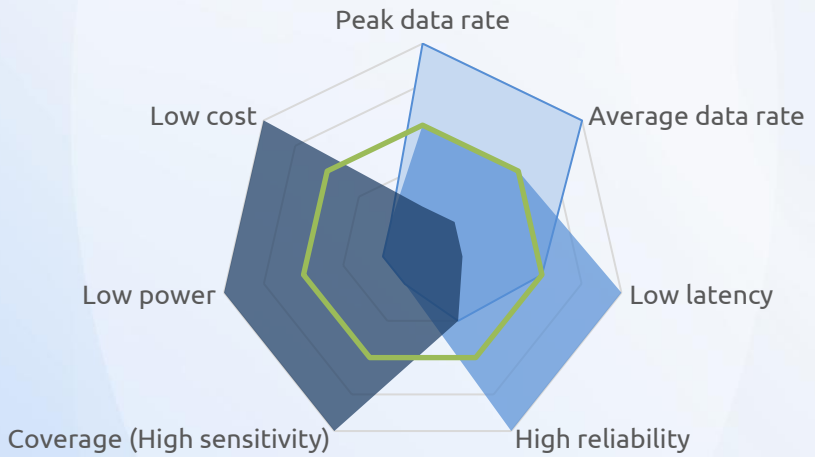
Source: Soitec

5G RedCap – EXPANDING 5G PENETRATION TO ADVANCED WEARABLES

MAKING 5G ACCESSIBLE & COST-EFFECTIVE, TOWARD A MORE CONNECTED WORLD

BALANCING PERFORMANCE, COST & POWER

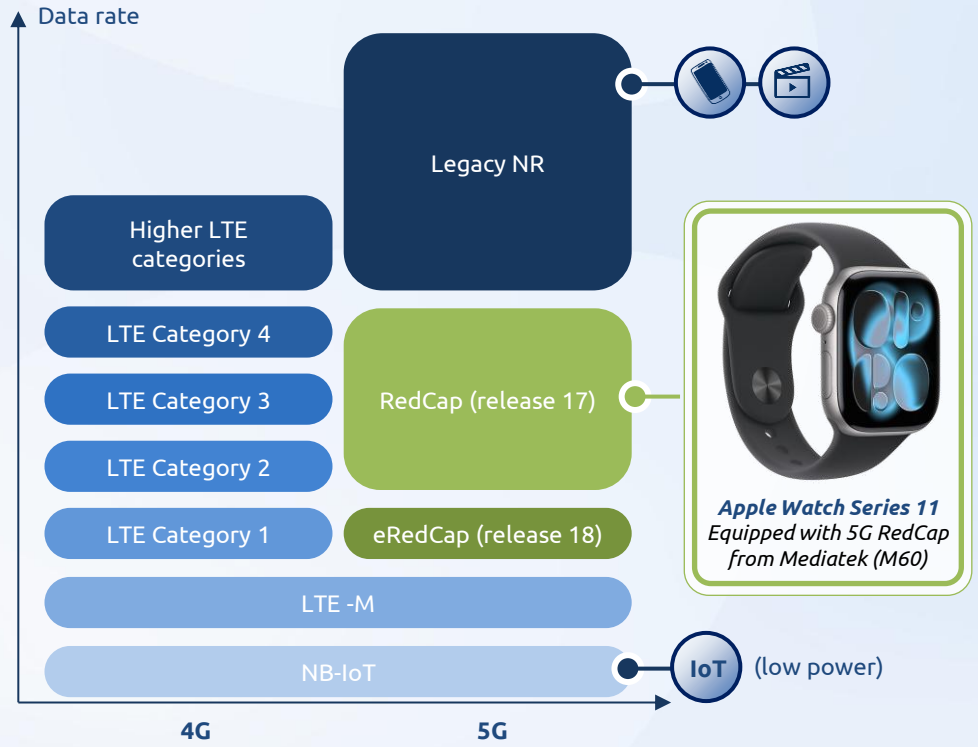
Simplifying RF complexity, reducing power consumption & cost to address advanced wearables & industrial efficiency



- eMBB — Enhanced Mobile Broadband – 4G evolution (much faster & higher capacity)
- uRLLC — Ultra-Reliable Low Latency Communications – typically used in AV, robotics
- mMTC — Massive Machine Type Communication – designed for IoT
- RedCap — Reduced Capacity – for advanced wearables

BRIDGING THE GAP BETWEEN HIGH-SPEED 5G & LOW-POWER IoT

eRedCap (R18) further simplifies RF complexity and reduce power consumption to extend 5G penetration to mid-tier advanced wearables



Apple Watch Series 11
Equipped with 5G RedCap from Mediatek (M60)

Source: GSMA 2025, Navian 2025

AI x CONNECTIVITY – ENHANCING Wi-Fi PERFORMANCE

ENABLING GREATER USER EXPERIENCES

Wi-Fi 6 / 6E / 7 pave the way for new wireless connectivity
Wi-Fi 8 is on the way

Driving innovation to enhance wireless connectivity for new experiences and extended range

Wi-Fi 8 — Immersive communication Ultra-low latency

Wi-Fi 7 — Extremely High Throughput, low latency and/or high reliability for demanding applications from VR/AR to industrial IoT

Wi-Fi 6E — Adding 1GHz spectrum in the 6GHz band for higher quality of service (QoS) and secured connectivity

Wi-Fi 6 — High-speed connectivity technology in 2.4GHz and 5GHz bands for **smartphone, laptop, home, consolidating its place in smart home, wearables and automotive**

2019 2020 2021 2022 2023 2024 2025 2026 2027 2028 2029 2030+

Wi-Fi FRONT-END-MODULE SEMICONDUCTOR MARKET

Source: Soitec

EXPANDING MOBILE COMMUNICATIONS, ENVIRONMENTS

FIXED WIRELESS ACCESS (FWA)

Last-mile technology with fiber-like data speeds via 5G

New indoor opportunities (smart homes, factories, cloudification…)

Virtual lag-less experiences

FWA connections (millions)

Ericsson expects FWA data traffic at the end of 2025 to represent >25% of global mobile data traffic and is projected to grow by a factor of > 3 by the end of 2031

Source: Yole, Ericsson Mobility Report 2025

ACROSS HOMES, ENTERPRISES & REMOTE

NON-TERRESTRIAL NETWORK (NTN)

New NTN bands enabling global coverage

Relies on fully integrated SoC solutions

Requires low energy power consumption solutions

Smartphones with satellite connectivity (Mu)

Yole expects all new iPhones to be equipped with a satellite chipset at least until 2029

02 ENGINEERED SUBSTRATES OPPORTUNITIES

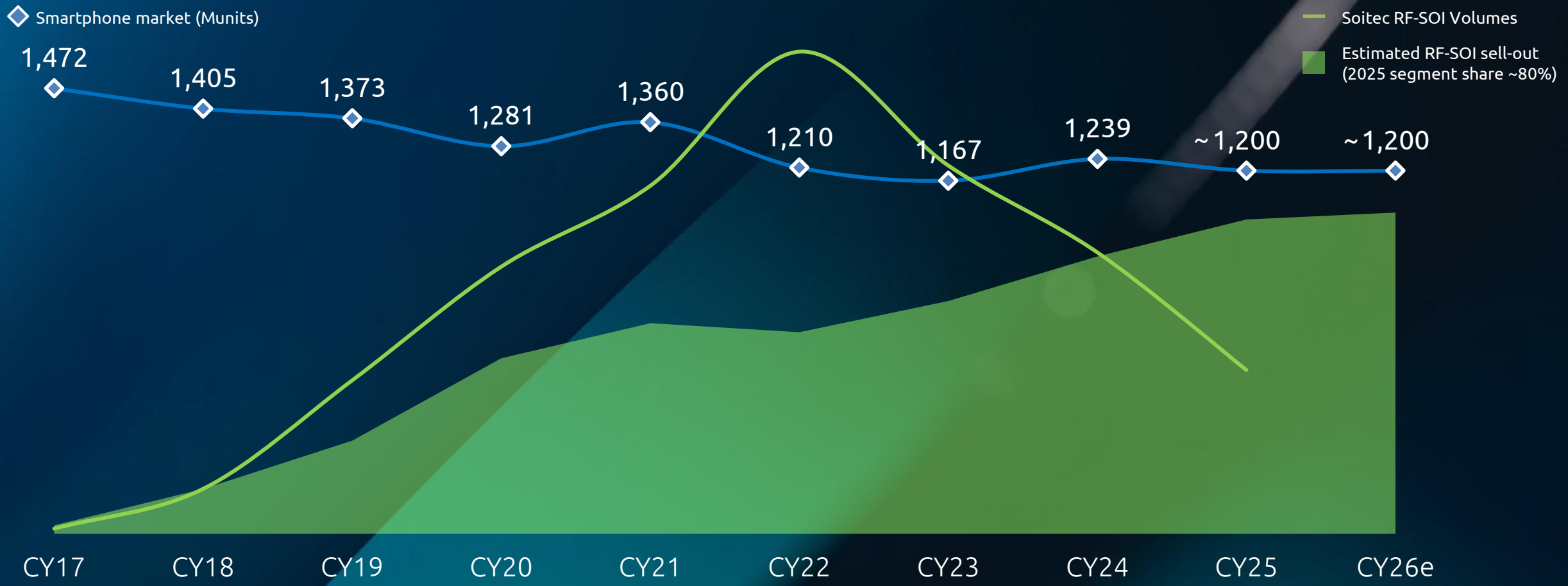
SMARTPHONE MARKET CHALLENGED AMIDST MEMORY SHORTAGE

5G PENETRATION MODERATE GROWTH

Source: IDC, Soitec

CUSTOMER INVENTORIES HEADING IN THE RIGHT DIRECTION

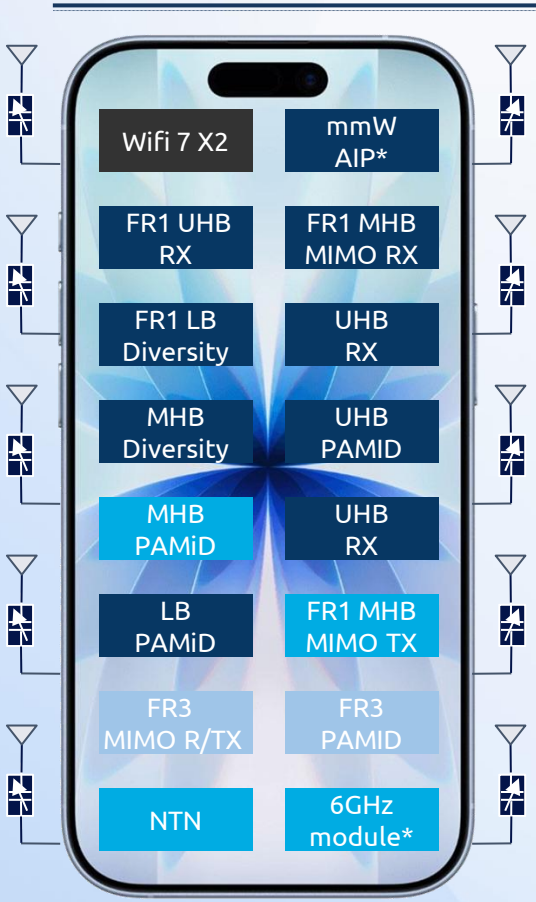
SIGNIFICANT UNDERSHIPMENT TO SUPPORT CUSTOMER INVENTORY CORRECTION



Source: Soitec

RFFE EVOLUTION – THE "UPLINK FIRST" ARCHITECTURE
TO SUPPORT INCREASING DATA TRAFFIC DRIVEN BY AI DEMAND

Future RFFE



- Power class 2 devices → Higher power output for better coverage
- UL MIMO* Requiring additional TX chains → Enhanced uplink data rate
- 6GHz bands introduction → Higher bandwidth to handle exponential growth in data
- FR3 bands introduction → Increased capacity to handle exponential growth in data

Current content
5G upgrade
6G upgrade

Lower insertion losses
Better thermal management
→ Value creation opportunity

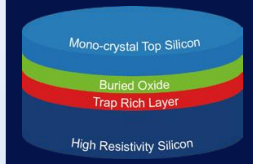
Content growth
Footprint optimization

Source: Soitec, Apple

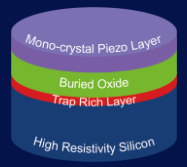
**Uplink Multiple Input Multiple Output*

WIRELESS CONNECTIVITY IN SMARTPHONES

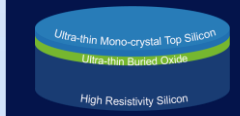
A COMPREHENSIVE OFFER FOR Sub-6GHz & mmWave FRONT-END MODULES



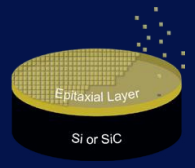
RF-SOI
For highly efficient mobile communications



POI
High performance 5G filters



FD-SOI
Integrated technology



RF-GaN
High-performance power amplifiers

TODAY'S SMARTPHONE: MORE EFFICIENT, LOWER POWER CONSUMPTION, SMALLER FOOTPRINT

	4G / 5G Sub-6GHz	5G mmWave	Wi-Fi & UWB
POWER AMPLIFIER (PA)		● ●	●
LOW NOISE AMPLIFIER (LNA)	●	● ●	●
SWITCH	●	●	●
ANTENNA TUNER (AT)	●		
FILTER	●		●
ENVELOPE TRACKER (ET)	●		
PHASE SHIFTER		● ●	●
SYSTEM ON CHIP (SoC)		●	●
INTEGRATED FRONT-END	●	●	● ●

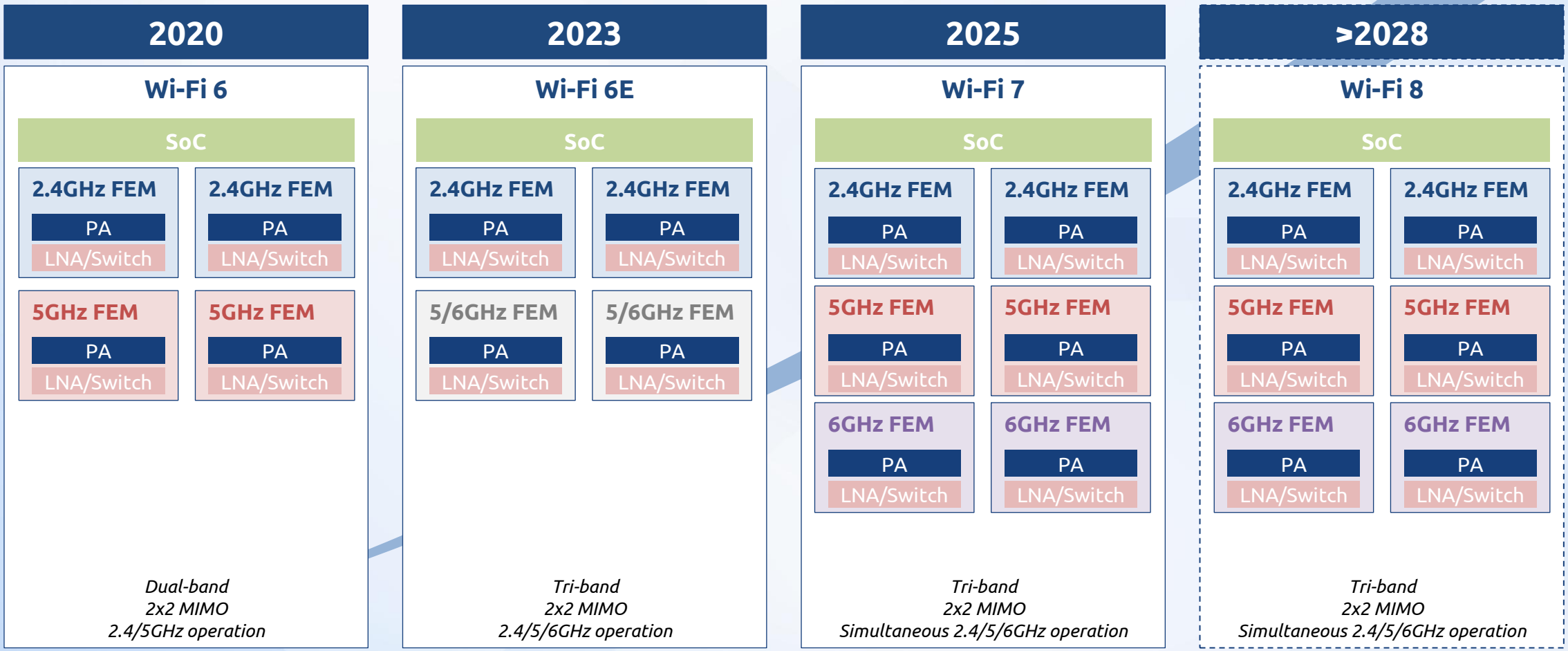
TOMORROW'S SMARTPHONE – MORE DATA, MORE BANDS: ADDITIONAL CONTENT TO THE FRONT-END MODULE

	5G	5G Advanced	6G
mmW ANTENNA IN PACKAGE	●	●	●
MIMO UHB	● ●	● ● ●	● ● ●
MIMO MB/HB	● ● ●	● ● ●	● ● ●
MIMO LB	● ● ●	● ● ●	● ● ●
NTN SOS & VOICE	● ●	● ●	● ●
NTN DATA		● ●	● ● ●
MIMO NEW 6GHz BANDS		● ● ●	
MIMO FR3			● ● ● ●

● RF-SOI ● FD-SOI ● POI ● RF-GaN

Wi-Fi 7/8 – FRONT END MODULE TRANSITION

UNLEASHING Wi-Fi FULL POTENTIAL WITH HIGHER CONTENT



Source: Yole 2024, Soitec consolidation

WIRELESS CONNECTIVITY IN AUTOMOTIVE

INFOTAINMENT
in-vehicle

Internet services
Navigation system
Screen mirroring

Hands free voice
Multimedia streaming

TELEMATICS
cloud ↔ vehicle
satellite ↔ vehicle

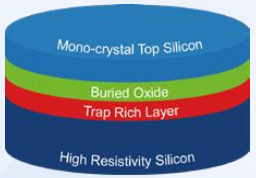
OTA Update
Vehicle location
Optimum routing

Internet access
Fleet utilization
Media services

ENVIRONMENT
V2x

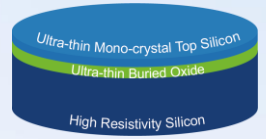
Dynamic traffic signage
Connection to home
Pedestrian warning

Driver assistance
Remote control
Keyless access



RF-SOI
Extended High performance RFFE for connectivity,
C-V2X & 5G in automotive

FD-SOI
Extensive SoC solution from connectivity to MCU/PMU edge computing



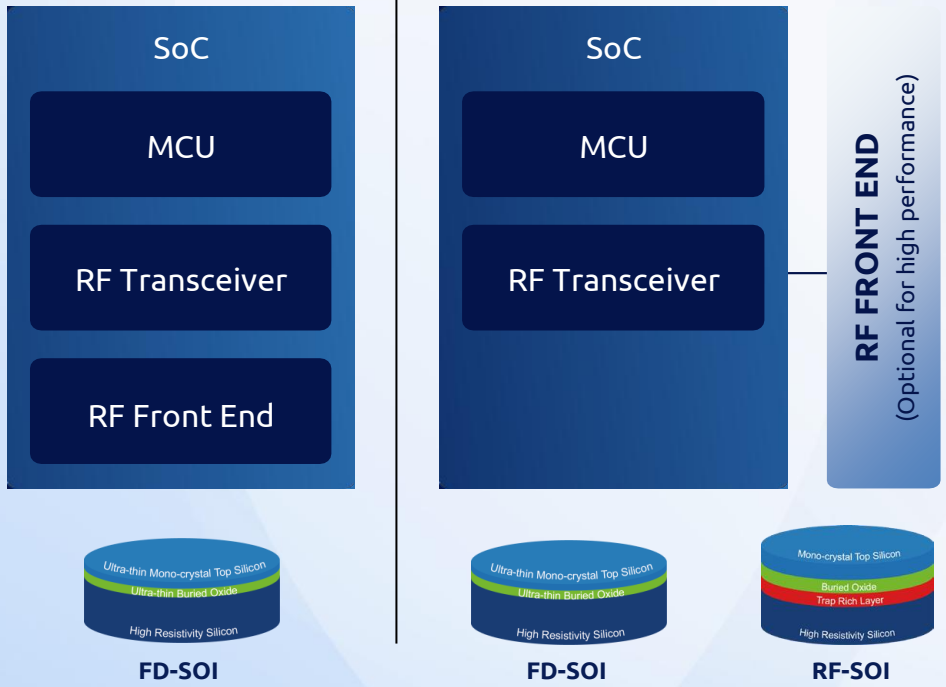
WIRELESS CONNECTIVITY IN SMART DEVICES

ENABLING WIRELESS FUNCTIONALITIES AT LOW POWER CONSUMPTION

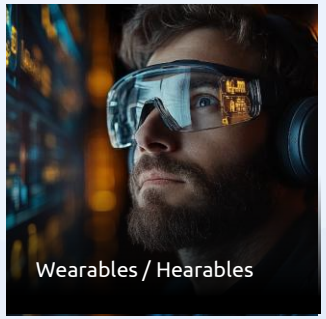
WIRELESS MODULES

MAINSTREAM
with integrated RFFE and low power consumption

HIGH END
with externalized RFFE and extended RF performances



POWER EFFICIENT WIRELESS SOLUTIONS SUPPORTING A WIDE RANGE OF APPLICATIONS



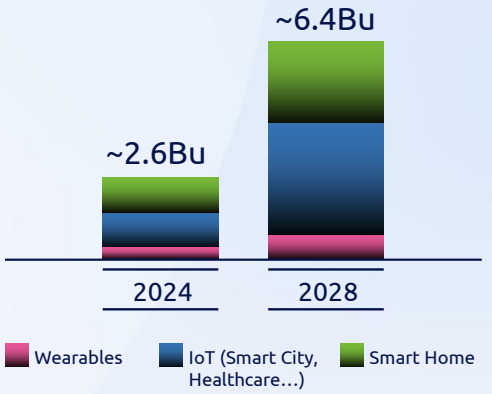
SOI ENGINEERED SUBSTRATES ENABLE BETTER SMART DEVICES

BATTERY POWER SAVINGS

INTEGRATION FROM SOC TO MODULE

SIGNAL INTEGRITY WITH MULTI CONNECTIVITY PROTOCOLS

CONNECTIVITY WIRELESS SMART DEVICES



Source: ABI, 2024

AI SMART GLASSES – ENABLING STANDALONE AR WITH ENGINEERED SUBSTRATES

FROM SMARTPHONE COMPANION TO STANDALONE AR CONNECTIVITY

TODAY: THE SMARTPHONE COMPANION

Meta Ray-Ban Display

Compact form factor / Light
Wi-Fi / Bluetooth connectivity
Processing capability
Long battery life

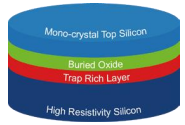
NEXT-GENERATION: ENHANCED CONNECTIVITY

RayNeo X3 Pro

Compact form factor / Light
Wi-Fi / Bluetooth connectivity
+ 4G LTE and 5G RedCap
Processing capability
Long battery life

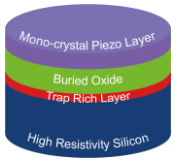
SOITEC CONNECTIVITY SOLUTIONS

RF-SOI



- Best-in-class RF performance
- Lower latency for real-time applications
- Reduced power consumption
- Better thermal management
- Smaller footprint

POI

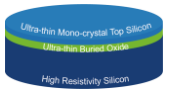


Optimal solution for advanced SAW filters

- Can operate across the entire spectrum
- Improved coupling
- Lower insertion losses
- Better thermal management
- Better integration

SOITEC COMPUTING SOLUTION

FD-SOI



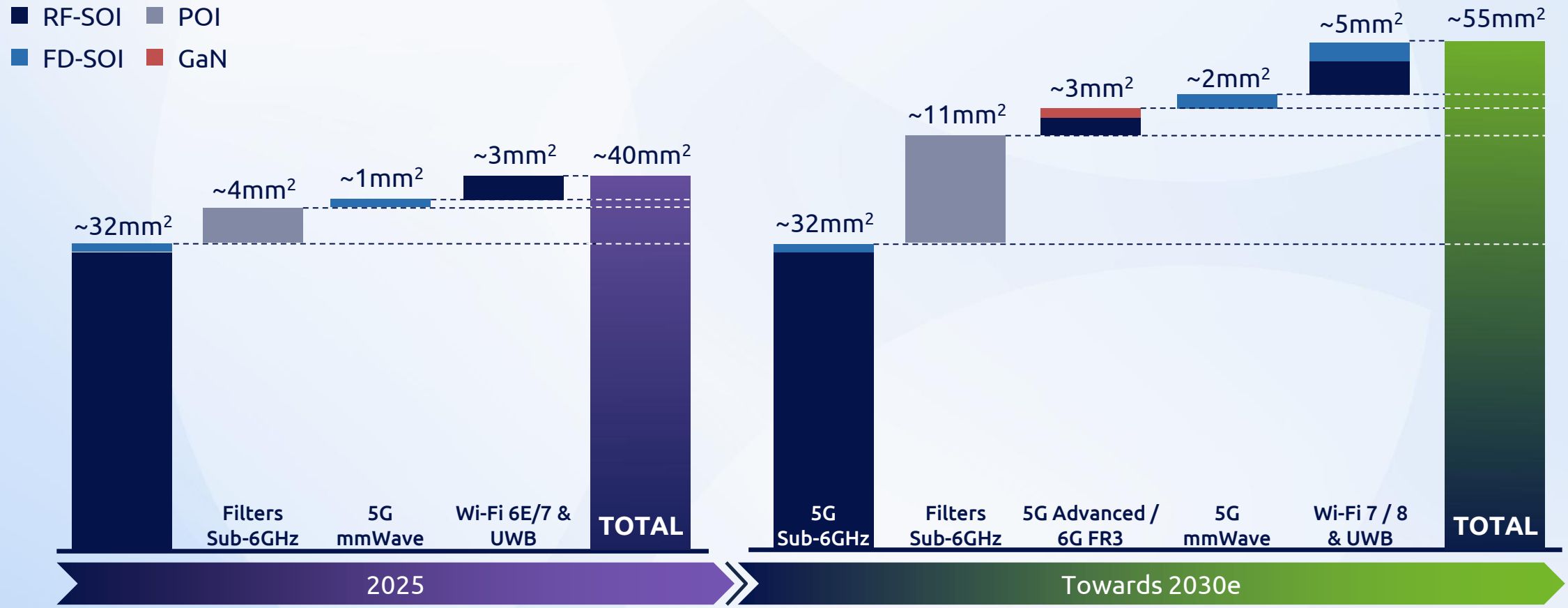
- Energy efficiency / low-leakage
- Always-on / on-demand performance
- Low power consumption
- Greater integration / compacity

Source: Meta, NXP, RayNeo, Soitec

TEARDOWNS CONFIRM SOITEC CONTENT IN ALL 5G SMARTPHONES

AVERAGE ACTUAL SOITEC CONTENT PER SMARTPHONE (mm²)

Average of All smartphones



Source: Soitec

03

SOITEC TECHNOLOGY LEADERSHIP ACCELERATES AI x CONNECTIVITY CONVERGENCE

INNOVATION TO SUPPORT CONTENT GROWTH AND VALUE CREATION

ENGINEERED SUBSTRATES ENABLE NEXT-GENERATION DEVICES

Enhanced connectivity & user experience

AI & ML
5G NR-U (6GHz)
5G FR3 (10-20GHz)
Wi-Fi 7

UWB
NTN 3GPP & proprietary sub-6GHz & mmWave

Enabling new technology differentiation for our customers

3D-stacking
Footprint optimization (die shrink)
Technology scaling (higher frequencies)

Foundry yield improvement

Advanced RF Performances

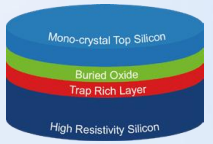
Enabling new devices

Form factor: increasing foldable phone market share leads to increasing antenna integration challenges

New devices (smart glasses, wearables) requiring optimized footprint

RF-SOI

RF-SOI EMBEDDED IN 100% OF 5G SMARTPHONES



RF-SOI EXPANDING LEADERSHIP INTO NEW 5G VERTICALS

5G Communications

Automotive & Industry 4.0

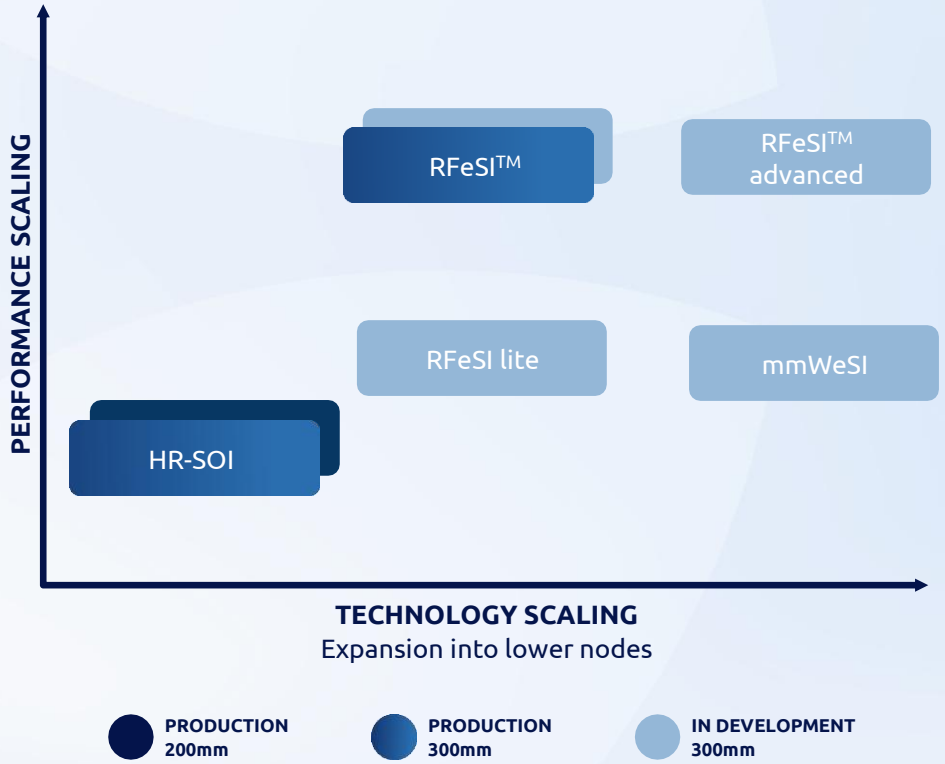
AR / VR

Fixed Wireless Access

OUR RF-SOI SUBSTRATES ENABLE

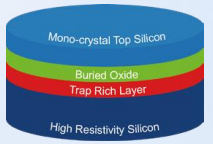
- 5G Connectivity Enhancement
- Battery Power Saving
- Optimized Footprint with RFFE Integration

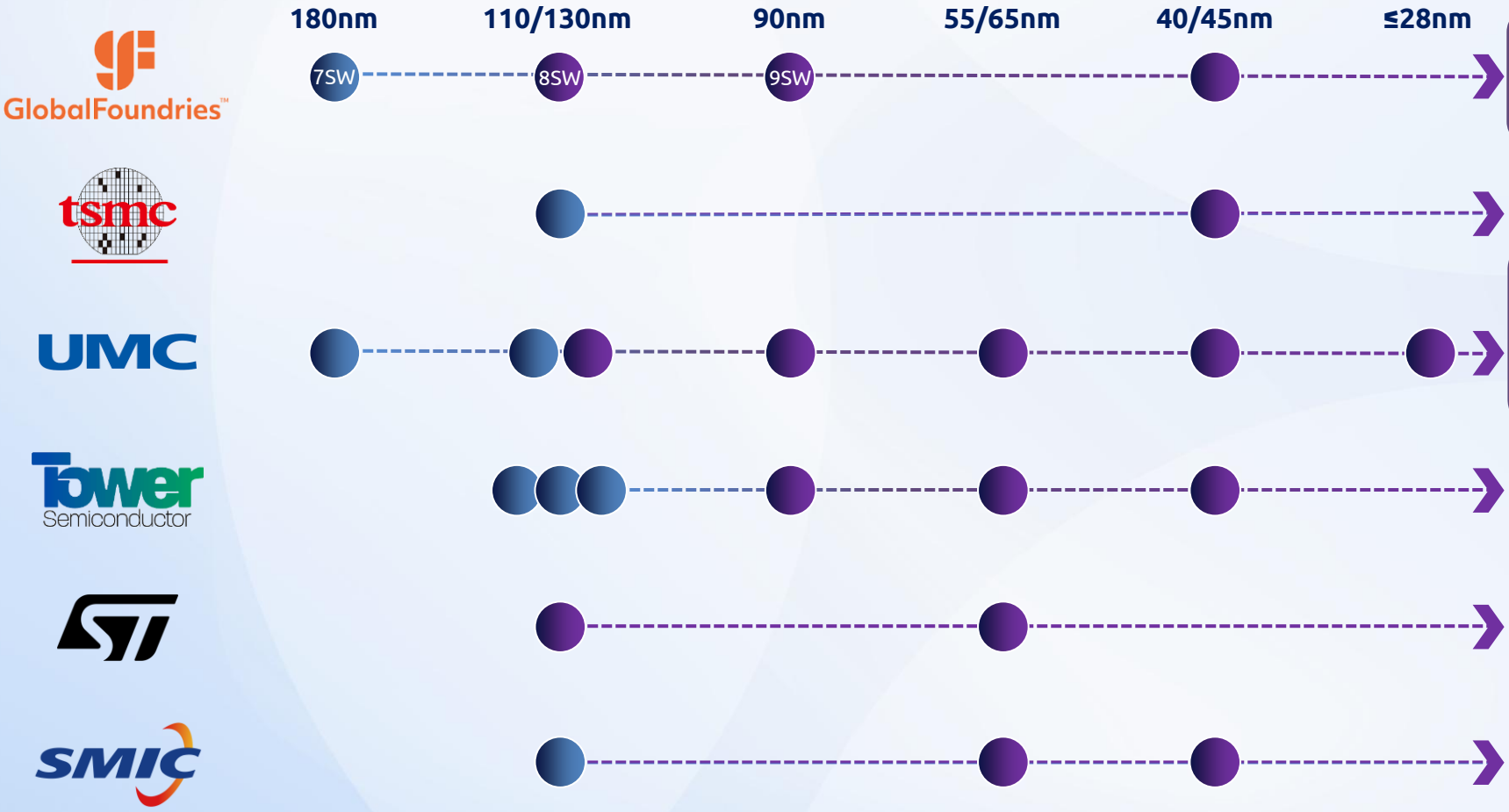
RF-SOI ROADMAP



RF-SOI 300mm ACCELERATED TRANSITION

SUPPORTING FOUNDRIES ROADMAP & ENABLING DIFFERENTIATION





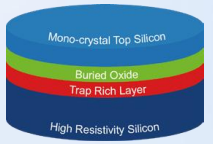
"This collaboration with Soitec shows our commitment to ensure a continuous supply of high-performance RF-SOI solutions that meet our customers' fast evolving needs"

"Leveraging our strong partnership with Soitec, UMC's innovative 3D IC solution for RF-SOI has generated significant interest from customers as they seek to integrate more RF components in 5G-enabled wireless devices"

"The unique advantages of Tower's RF-SOI technology have enabled Broadcom to design and bring to market a set of compact, high-performance FEMs for Wi-Fi 7 mobile applications"

Source: Yole, Soitec, Company website

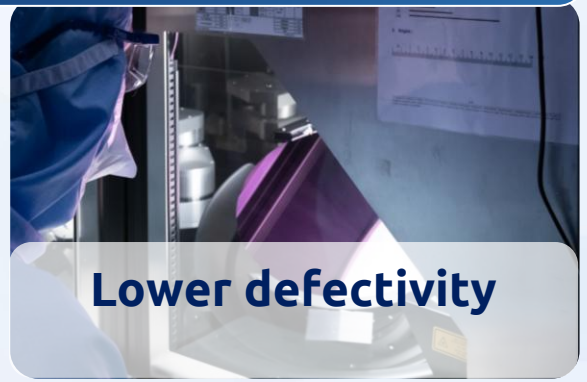
300mm ACCELERATES TECHNOLOGY DIFFERENTIATION AND UNLOCKS BETTER ECONOMICS



TECHNOLOGY DIFFERENTIATION

Latest-generation
tools & processes

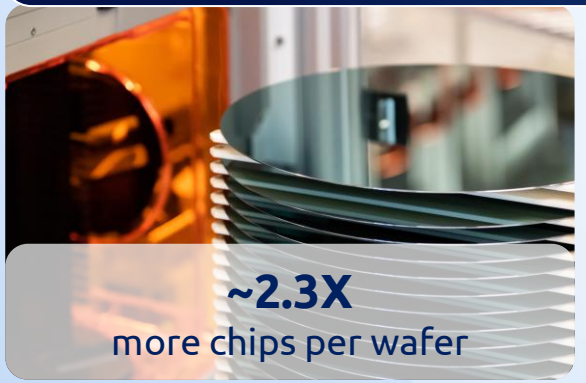
Better Uniformity



Lower defectivity

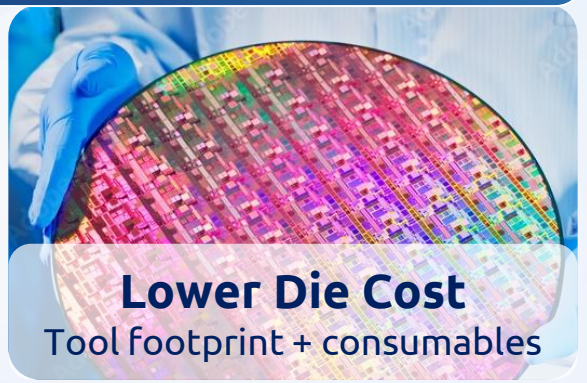
Compatibility with lithography tools
For leading edge applications

BETTER ECONOMICS



~2.3X
more chips per wafer

Fully automated fab
increasing throughput & yield



Lower Die Cost
Tool footprint + consumables

INNOVATION IN 300mm RF-SOI ACCELERATING THE AI x CONNECTIVITY CONVERGENCE

LEADING THE RF-SOI EVOLUTION

GenAI + extension to new form factors

Transforming mobile networks from content delivery platforms into real-time distributed AI systems

ENHANCED CONNECTIVITY

AI at the EDGE

FOUNDRIES

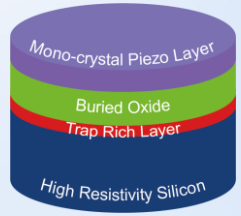
- Advanced node processing (CMOS sub-45nm)
- Enhanced signal integrity / linearity to enable 5G advanced / 6G
- Reduced insertion losses to optimize power consumption
- Footprint optimization with 3D integration (3D IC by UMC x Soitec)

300mm RF-SOI

- Superior uniformity across 300mm
- Ensure overlay robustness
- Enhanced trap-rich performance
- Improved high resistivity Si layer
- Improved BOX performance
- Roadmap to enable 3D RF-SOI

POI

POI FOR ADVANCED RF FILTERS ADOPTED BY MAIN OEMs



iPhone 16e

Google Pixel 9
Google Pixel 9 Pro

Google Pixel
9 Pro Fold

Samsung
Galaxy Z Flip5

Ray-Ban Meta

OUR POI SUBSTRATES ENABLE

- Better Filter Performance
- Battery Power Saving
- Optimized Filter BOM Footprint

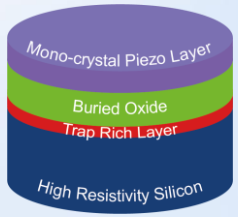
Source: Samsung, Google, Apple, Ray-Ban

POI ROADMAP

LB: Low Band (0.6-1GHz), **MHB:** Mid-High Band (1.4-2.7GHz), **UHB:** Ultra High Band (>3.3GHz)
LN: Lithium Niobate on Insulator, **LT**: Lithium Tantalate on Insulator

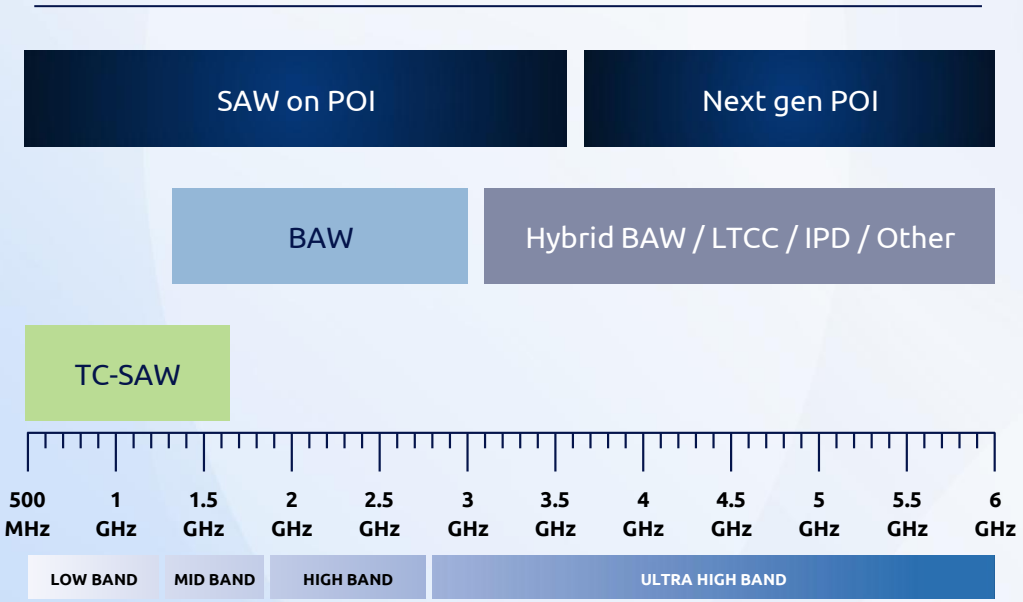
POI

WHY POI?



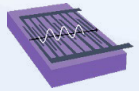
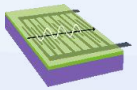
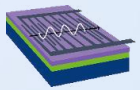
SAW-ON-POI CAN OPERATE ACROSS THE WHOLE FREQUENCY SPECTRUM

Enabling transition to higher bands



SAW-ON-POI ADDRESSES ALL 5G FILTER NEEDS

From higher selectivity to lower insertion losses,
enhanced frequency stability and easier multiplexer integration

	 SAW	 TC-SAW	 BAW	 SAW-on-POI
Substrate	Piezo (non-POI)	Piezo (non-POI)	Piezo (non-POI)	POI
Quality Factor	=	−	+	+
Coupling factor	=	−	=	+
Temperature Compensation	=	+	=	+
Process simplicity	=	−	−	=
Integration	=	=	=	+

POI

STRONG VALUE FOUNDATION FOR MARKET EXPANSION

POI customer testimony

> Tier #1 US: *a* ***"Performance play"***
> Tier #1 US: *Soitec POI perform "****better than TC-SAW****"*
> Tier #1 US: "***better Qmax than equivalent BAW technology***"
> Tier#2 China: *Soitec POI is* ***considered as a "reference"***

13 customers in Production

9 customers in Qualification

Engaged with all key players

Google Pixel 9 integrates POI from Qorvo & Skyworks

LEADING RF FILTER MANUFACTURERS INTEGRATE SOITEC POI FROM LOW- TO MID-HIGH BANDS

> *The trend towards using multilayer SAW filters is occurring in flagship smartphones like the Google Pixel 9. Yole Group has identified* ***piezoelectric on insulator (POI) SAW filters in the Google Pixel 9 smartphone supplied by Qorvo and Skyworks****.*

Source: Yole, Google

INNOVATION IN POI – ADDRESSING INCREASINGLY COMPLEX RFFE

UPGRADING THERMAL MANAGEMENT PERFORMANCES & EXPANDING TO HIGHER FREQUENCIES

GenAI + extension to new form factors

Transforming mobile networks from content delivery platforms into real-time distributed AI systems

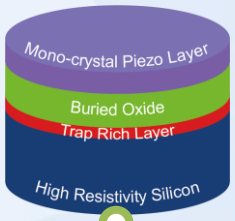
ENHANCED CONNECTIVITY

AI at the EDGE

FILTERS

- **Better thermal management** to handle high power 5G signals
- **Optimized footprint** with extended multiplexing
- **Reduced insertion losses** for high power class (PC2) devices
- **Extended frequency range & bandwidth** to address a growing data load

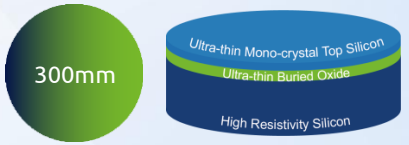
POI



- Enhanced TCF management
- Thin layer engineering
- New LNO top layer roadmap
- Waveguide performance

FD-SOI

FD-SOI FOR mmWave ENDORSED BY MAJOR SMARTPHONE OEMs




Samsung Galaxy S25


Google Pixel 9
Google Pixel 9 Pro


Google Pixel 9 Pro Fold


Samsung Galaxy S24


Google Pixel 8
Google Pixel 8 Pro


Google Pixel Fold


Samsung Galaxy Z Flip 6


Samsung Galaxy Z Fold 6


Samsung Galaxy A53

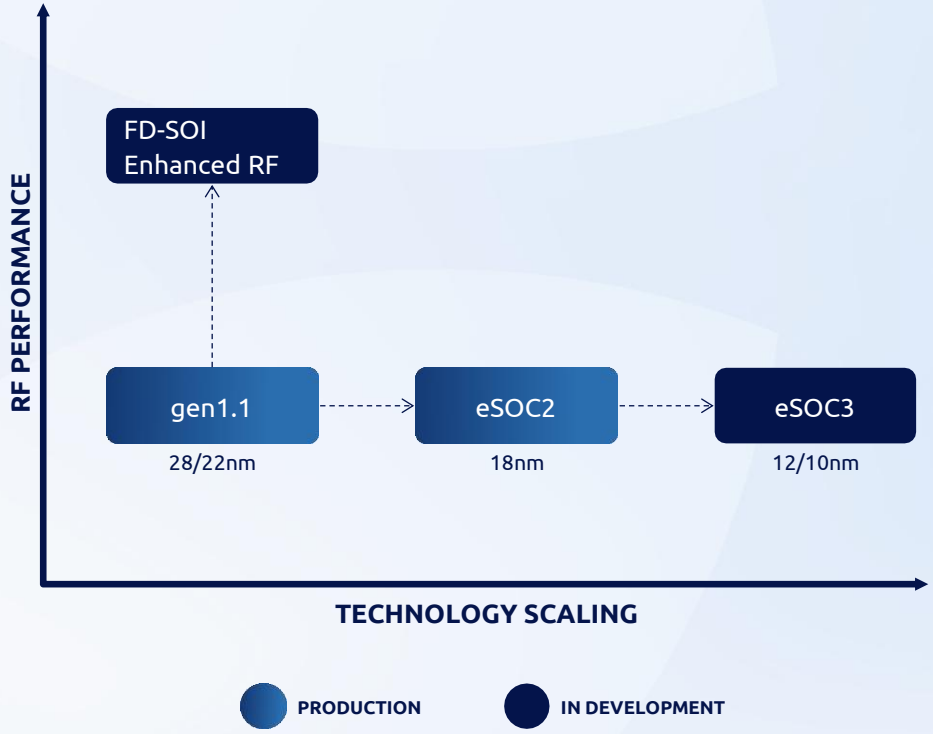

Google Pixel 7
Google Pixel 7 Pro


Google Pixel 6
Google Pixel 6 Pro

OUR FD-SOI SUBSTRATES ENABLE

- High Quality & Extended 5G mmWave Link
- >10% Battery Power Saving
- Optimized Footprint with Digital Scaling

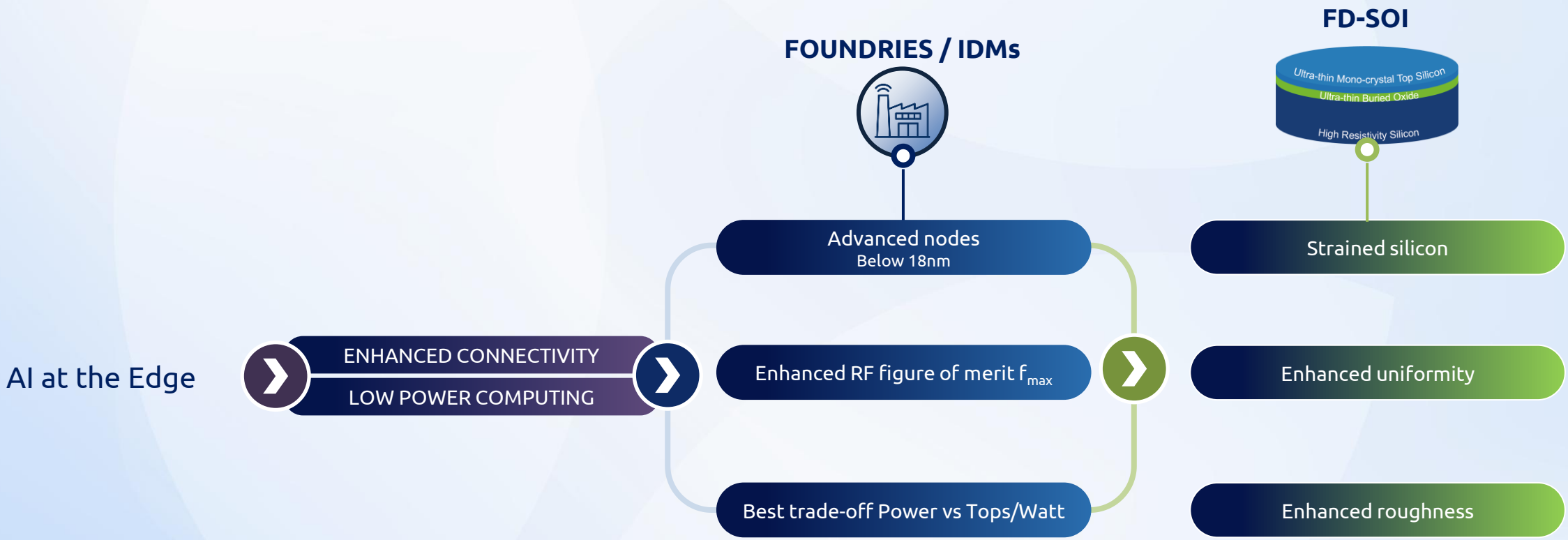
FD-SOI ROADMAP



Source: Samsung, Google

INNOVATION IN FD-SOI – TOWARDS 18nm NODE

ENABLING THE TRANSITION TO 18nm AND BEYOND



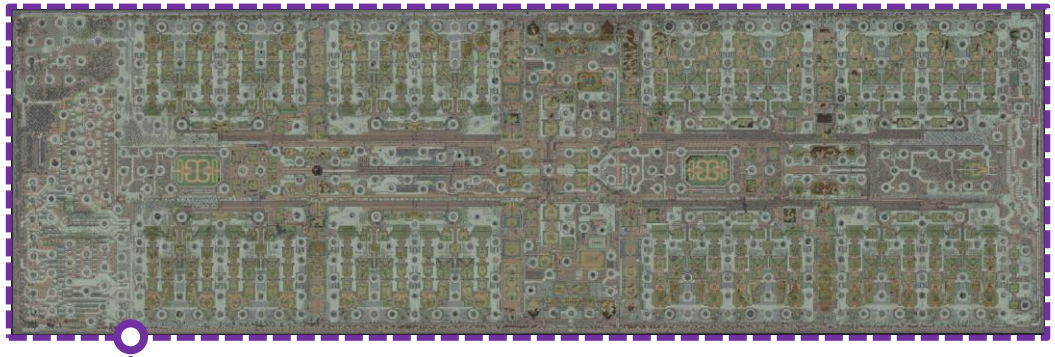
EXTENDING FD-SOI mmWave PENETRATION TO iPHONE

Techinsights x Yole teardowns & analysis reveal the 5G mmWave antenna module in the iPhone 17, iPhone 17 Pro and iPhone 17 Pro Max relies on Soitec state-of-the-art FD-SOI

mmWave AiP*

FD-SOI mmWave link

Qualcomm RFIC 22FDX from teardown of iPhone 17. Also found in other models



FD-SOI RFIC

Our FD-SOI enables

- High Quality & Extended 5G mmWave Link
- >10% Battery Power Saving
- Optimized Footprint with Digital Scaling

Source: TechInsights 2025, Yole, Soitec

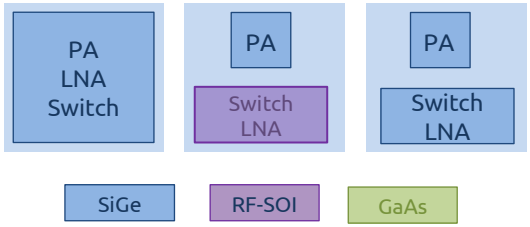
**AiP: Antenna-in-Package*

Wi-Fi: FROM A MULTI-DIE SOLUTION TO MONOLITHIC INTEGRATION WITH RF-SOI

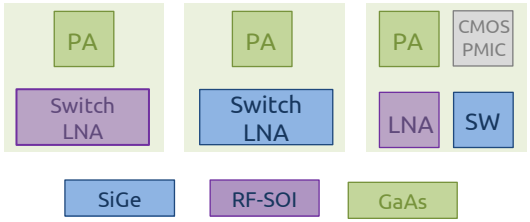
TEARDOWN OF GOOGLE PIXEL 9

From multi-dies Wi-Fi solution

SiGe based Wi-Fi die solution



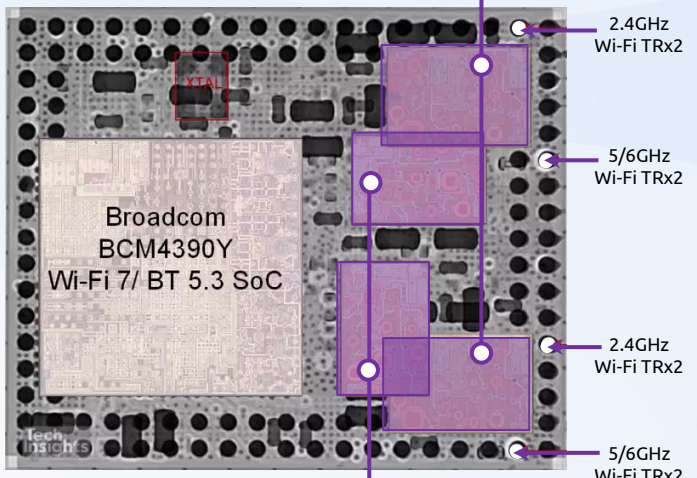
GaAs based Wi-Fi die solution



…to full RF-SOI die solution

USI G6-602650 Wi-Fi 7/BT 5.3 Module found in Google Pixel 9 Pro XL & others

Broadcom + Tower Semiconductor
5-7GHz **RF-SOI PA+LNA+ Switch** RFFE

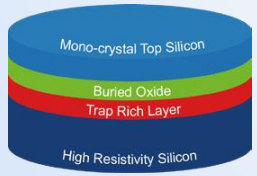


Broadcom + Tower Semiconductor
2.4GHz **RF-SOI PA+LNA+ Switch** RFFE

Source: Soitec

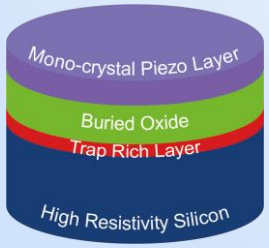
SOITEC EXTENDS ITS FOOTPRINT
KEY DESIGN-WINS ANNOUNCEMENTS OVER THE PAST 2 YEARS

300mm RF-SOI



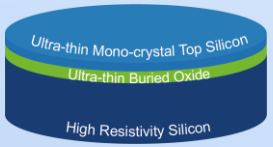
- UMC: New RF-SOI standard with Broadcom's **Wi-Fi** RFFE modules for next gen mobile applications
- Tower Semiconductor / BROADCOM: New RF-SOI standard with Broadcom's WiFi RFFE modules for next gen applications
- GlobalFoundries: Advanced **9SW** platform to use Soitec's latest generation of 300mm RF-SOI
- 3D IC antenna tuners in **iPhone 17**
- Pixel: Design wins for full RFFE Wifi 7 RF-SOI

POI



- SKYWORKS / Qorvo: **Google Pixel 9 & 10** integrate POI from Skyworks x Qorvo
- Multiple design wins for PAMID **Chinese Android OEM** Mid-End to High-End
- Multiple design wins in the **iPhone 17**
- Tier-1 US Fabless Move into volume production

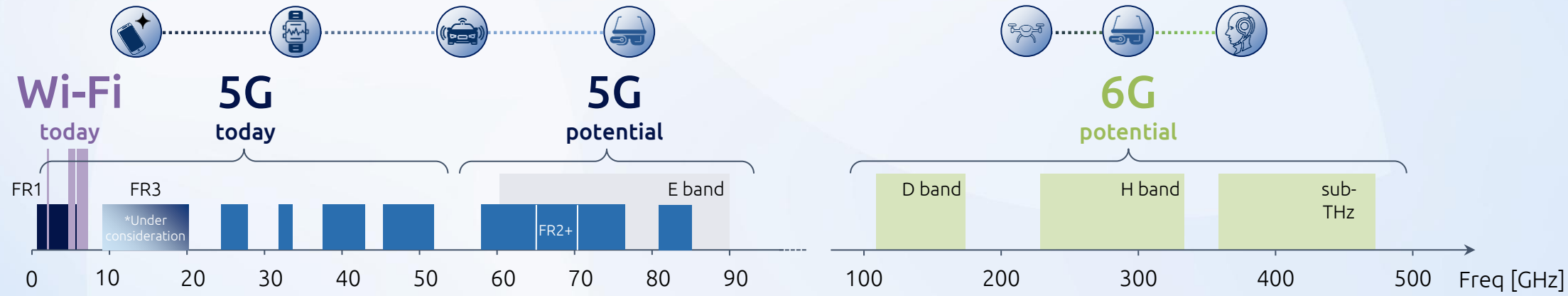
FD-SOI

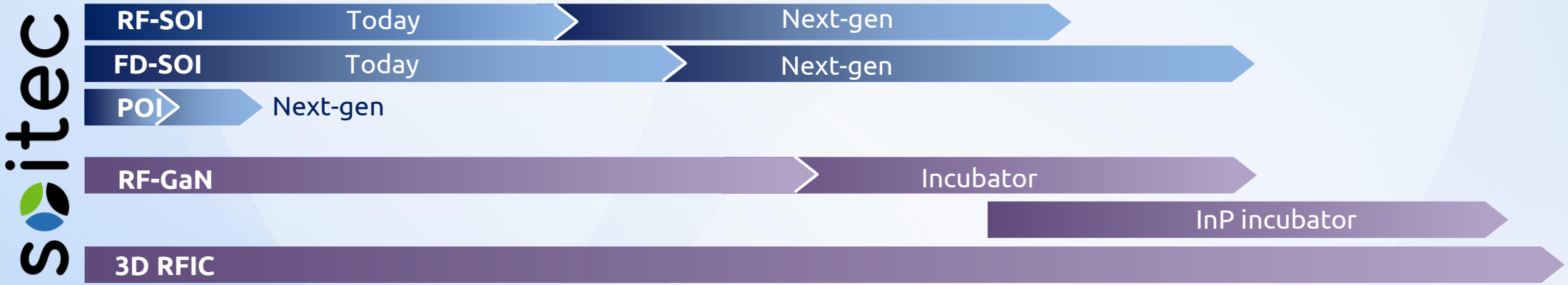


- SAMSUNG: 5G mmWave design wins in **Samsung S25 & Z Fold** US modules
- MEDIATEK: Design wins for Wi-Fi 7 SoC transceiver premium android smartphone
- 5G mmWave & envelope tracker design wins in the **iPhone 17**
- STMicroelectronics / STARLINK: Design wins for MCU

PERFORMANCE ALWAYS STARTS WITH HARDWARE

SOITEC PRODUCT ROADMAP EXPANDS ADDRESSABLE MARKET





Source: Qualcomm, Ericsson, Soitec

AI x CONNECTIVITY POWERED BY ENGINEERED SUBSTRATES

THANK YOU

GLOSSARY

4G LAA	4G License Assisted Access
4G LTE	4G Long-Term Evolution
5G NR-U	5G New Radio Unlicensed
AiP	Antenna-in-Package
BAW	Bulk Acoustic Wave
CPE	Customer Premises Equipment
FTTX	Fiber-to-Anything
FWA	Fixed Wireless Access
IPD	Integrated Passive Devices
LB	Low Band
LNA	Low Noise Amplifier
LTCC	Low Temperature Co-fired Ceramic
MCU	Microcontroller Unit
MHB	Mid-High Band
NTN	Non-Terrestrial Network
RFFE	RF Front-End
SAW	Surface Acoustic Wave
SoC	System-on-Chip
TC-BAW	Temperature Compensated BAW
UHB	Ultra-High band
UWB	Ultra-Wide band
UL MIMO	Uplink Multiple Input Multiple Output
V2x	Vehicle-to-Everything